

Abstract

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10 A circuit board (5) is described, consisting of at least two individual circuit board layers (10) made of plastics and produced by formation technique, which each have first and second functional sides and at least one microstructured positioning formation (16) on each of the first and second functional sides and at least one microstructured conductor trench (12) on one of the functional sides, the conductor trench (12) being provided with a metallization (18). This allows a low expenditure production of circuit boards having a high packing density.

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~~Eig. 1~~

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